

2.5/3V, IS25Lx Family - Multi I/O Quad SPI (DTR Available in LP Series)

Den	Part Number	Vcc	Freq. (MHz)	Package Type	Temp. Range	Status
256K	IS25LQ025B	2.3V-3.6V	33/104	SOP (8) 208mil, SOP (8) 150mil, TSSOP, VVSOP (8) 150mil, WSON 6x5mm, USON 2x3mm, KGD	-40° to 125°C	Prod
512K	IS25LQ512B	2.3V-3.6V	33/104	SOP (8) 208mil, SOP (8) 150mil, TSSOP, VVSOP (8) 150mil, WSON 6x5mm, USON 2x3mm, KGD	-40° to 125°C	Prod
1M	IS25LQ010B	2.3V-3.6V	33/104	SOP (8) 208mil, SOP (8) 150mil, TSSOP, VVSOP (8) 150mil, WSON 6x5mm, USON 2x3mm, KGD	-40° to 125°C	Prod
2M	IS25LQ020B	2.3V-3.6V	33/104	SOP (8) 208mil, SOP (8) 150mil, TSSOP, VVSOP (8) 150mil, WSON 6x5mm, USON 2x3mm, KGD	-40° to 125°C	Prod
4M	IS25LQ040B	2.3V-3.6V	33/104	SOP (8) 208mil, SOP (8) 150mil, TSSOP, VVSOP (8) 150mil, WSON 6x5mm, USON 2x3mm, KGD	-40° to 125°C	Prod
8M	IS25LP080D	2.3V-3.6V	50/133	SOP (8) 208mil, SOP (8) 150mil, VVSOP (8) 150mil, WSON 6x5mm, USON 4x3mm, USON 2x3mm, KGD	-40 to 125°C	Prod
16M	IS25LP016D	2.3V-3.6V	50/133	SOP (16) 300mil, SOP (8) 208mil, SOP (8) 150mil, VVSOP (8) 150mil, WSON 6x5mm, USON 4x3mm, USON 2x3mm, BGA (24), KGD	-40° to 125°C	Prod
32M	IS25LP032D	2.3V-3.6V	50/133	SOP (16) 300mil, SOP (8) 208mil, SOP (8) 150mil, WSON 8x6mm, WSON 6x5mm, USON 4x3mm, BGA (24), KGD	-40° to 125°C	Prod
64M	IS25LP064A	2.3V-3.6V	50/133	SOP (16) 300mil, SOP (8) 208mil, WSON 8x6mm, WSON 6x5mm, BGA (24), KGD	-40° to 125°C	Prod
128M	IS25LP128F	2.3V-3.6V	50/133	SOP (16) 300mil, SOP (8) 208mil, WSON 8x6mm, WSON 6x5mm, BGA (24), KGD	-40° to 125°C	Prod
256M	IS25LP256D	2.3V-3.6V	80/166	SOP (16) 300mil, WSON 8x6mm, BGA (24), KGD	-40° to 125°C	Prod

1.8V, IS25Wx Family - Multi I/O Quad SPI (DTR Available in WP Series)

Den	Part Number	Vcc	Freq. (MHz)	Package Type	Temp. Range	Status
2M	IS25WQ020	1.65V-1.95V	33/104	SOP (8) 208mil, SOP (8) 150mil, VVSOP (8) 150mil, WSON 6x5mm, USON 2x3mm, KGD	-40° to 105°C	Prod
4M	IS25WQ040	1.65V-1.95V	33/104	SOP (8) 208mil, SOP (8) 150mil, VVSOP (8) 150mil, WSON 6x5mm, USON 2x3mm, KGD	-40° to 105°C	Prod
8M	IS25WP080D	1.65V-1.95V	50/133	SOP (8) 208mil, SOP (8) 150mil, VVSOP (8) 150mil, WSON 6x5mm, USON 4x3mm, USON 2x3mm, KGD	-40 to 125°C	Prod
16M	IS25WP016D	1.65V-1.95V	50/133	SOP (16) 300mil, SOP (8) 208mil, SOP (8) 150mil, VVSOP (8) 150mil, WSON 6x5mm, USON 4x3mm, USON 2x3mm, BGA (24), KGD	-40° to 125°C	Prod
32M	IS25WP032D	1.65V-1.95V	50/133	SOP (16) 300mil, SOP (8) 208mil, SOP (8) 150mil, WSON 8x6mm, WSON 6x5mm, USON 4x3mm, BGA (24), KGD	-40° to 125°C	Prod
64M	IS25WP064A	1.65V-1.95V	50/133	SOP (16) 300mil, SOP (8) 208mil, WSON 8x6mm, WSON 6x5mm, BGA (24), KGD	-40° to 125°C	Prod
128M	IS25WP128	1.65V-1.95V	50/133	SOP (16) 300mil, SOP (8) 208mil, WSON 8x6mm, WSON 6x5mm, BGA (24), KGD	-40° to 125°C	Prod
256M	IS25WP256D	1.65V-1.95V	80/166	SOP (16) 300mil, WSON 8x6mm, BGA (24), KGD	-40° to 125°C	Prod

Twin Serial NOR Flash (SPI)

Den	Part Number	Type	Vcc	Freq. [MHz]	Temp.Range	Package Type	Status
256M	IS25DLP256M	Multi I/O SPI x8, QPI, DTR	2.3-3.6V	80/166	-40 to 125°C	SOIC (16) 300mil, BGA (24)	S=2H/18
	IS25DWP256M	Multi I/O SPI x8, QPI, DTR	1.65-1.95V	80/166	-40 to 125°C	SOIC (16) 300mil, BGA (24)	S=2H/18
512M	IS25DLP512M	Multi I/O SPI x8, QPI, DTR	2.3-3.6V	80/166	-40 to 125°C	SOIC (16) 300mil, BGA (24)	Prod
	IS25DWP512M	Multi I/O SPI x8, QPI, DTR	1.65-1.95V	80/166	-40 to 125°C	SOIC (16) 300mil, BGA (24)	S=Q4/17

SLC NAND Flash

Den*	Part Number	Vcc	Ecc Requirement	Bus Width	Squential Read Speed (ns)	Temp.Range	Package Type	Status
1G	IS34ML01G081	3.3V	1-bit	X8	25	-40° to 105°C	48-TSOP, 63-BGA	Prod
	IS34ML01G084	3.3V	4-bit	X8	25	-40° to 105°C	48-TSOP, 63-BGA	Prod
	IS34MW01G084	1.8V	4-bit	X8	25	-40° to 105°C	48-TSOP, 63-BGA	Prod
	IS34MW01G164	1.8V	4-bit	X16	25	-40° to 105°C	48-TSOP, 63-BGA	Prod
2G	IS34ML02G081	3.3V	1-bit	X8	25	-40° to 105°C	48-TSOP, (63-BGA)	Prod
	IS34ML02G084	3.3V	4-bit	X8	25	-40° to 105°C	48-TSOP, (63-BGA)	Prod
	IS34MW02G084	1.8V	4-bit	X8	45	-40° to 105°C	48-TSOP, (63-BGA)	Prod
	IS34MW02G164	1.8V	4-bit	X16	45	-40° to 105°C	48-TSOP, (63-BGA)	Prod
4G	IS34ML04G081	3.3V	1-bit	X8	25	-40° to 105°C	48-TSOP	Prod
	IS34ML04G084	3.3V	4-bit	X8	25	-40° to 105°C	48-TSOP	Prod
	IS34MW04G084	1.8V	4-bit	X8	45	-40° to 105°C	48-TSOP	Prod
	IS34MW04G164	1.8V	4-bit	X16	45	-40° to 105°C	48-TSOP	Contact Factory

Flash

Automotive SLC NAND Flash

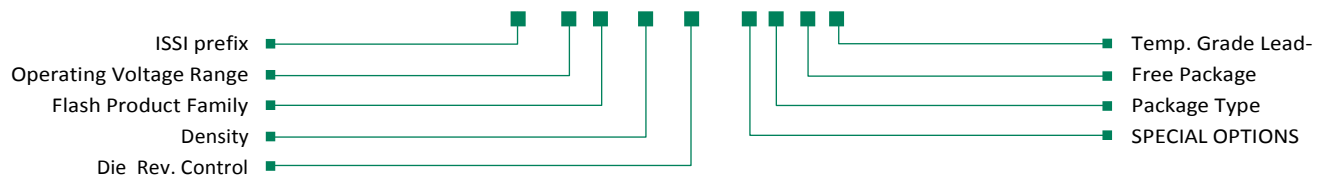
Den*	Part Number	Vcc	Ecc Requirement	Bus Width	Squential Read Speed (ns)	Temp.Range	Package Type	Status
1G	IS35ML01G081	2.7-3.6V	1-bit	X8	25	-40° to 85°C	48-TSOP, 63-BGA	Prod
	IS35ML01G084	2.7-3.6V	4-bit	X8	25	-40° to 85°C	48-TSOP, 63-BGA	Prod
	IS35MW01G084	1.7-1.95V	4-bit	X8	25	-40° to 85°C	48-TSOP, 63-BGA	Prod
	IS35MW01G164	1.7-1.95V	4-bit	X16	25	-40° to 85°C	48-TSOP, 63-BGA	Prod
2G	IS35ML02G081	2.7-3.6V	1-bit	X8	25	-40° to 85°C	48-TSOP, (63-BGA)	Prod
	IS35ML02G084	2.7-3.6V	4-bit	X8	25	-40° to 85°C	48-TSOP, (63-BGA)	Prod
	IS35MW02G084	1.7-1.95V	4-bit	X8	45	-40° to 85°C	48-TSOP, (63-BGA)	Prod
	IS35MW02G164	1.7-1.95V	4-bit	X16	45	-40° to 85°C	48-TSOP, (63-BGA)	Prod
4G	IS35ML04G081	2.7-3.6V	1-bit	X8	25	-40° to 85°C	48-TSOP	Prod
	IS35ML04G084	2.7-3.6V	4-bit	X8	25	-40° to 85°C	48-TSOP	Prod
	IS35MW04G084	1.7-1.95V	4-bit	X8	45	-40° to 85°C	48-TSOP	Prod
	IS35MW04G164	1.7-1.95V	4-bit	X16	45	-40° to 85°C	48-TSOP	Contact Factory

HyperFlash™

Den	Part Number	Type	Vcc	Freq. (MHz)	Temp. Range	Package Type	Status	Comment
128M	IS26KL128S	HyperFlash™	2.7-3.6V	100	-40 to 125 deg °C	BGA (24)	Prod	
	IS26KS128S	HyperFlash™	1.7-1.95V	166	-40 to 125 deg °C	BGA (24)	Prod	
256M	IS26KL256S	HyperFlash™	2.7-3.6V	100	-40 to 125 deg °C	BGA (24)	Prod	
	IS26KS256S	HyperFlash™	1.7-1.95V	166	-40 to 125 deg °C	BGA (24)	Prod	
512M	IS26KL512S	HyperFlash™	2.7-3.6V	100	-40 to 125 deg °C	BGA (24)	Prod	
	IS26KS512S	HyperFlash™	1.7-1.95V	166	-40 to 125 deg °C	BGA (24)	Prod	

Serial NOR Flash (SPI) Part Decoder

IS 25 L Q 020 B - J N L E



■ Operating Voltage Range

L = 2.3-3.6V
W=1.65-1.95V

■ Flash Product Family

Q = Single/Dual/Quad SPI
P = Single/Dual/Quad/QPI SPI
DTR Options Available

■ Die Rev. Control

Blank = First Rev.

■ Density

025 = 256Kb
512 = 512Kb
010 = 1Mb
020 = 2Mb
040 = 4Mb
080 = 8Mb
016 = 16Mb
032 = 32Mb
064 = 64Mb
128 = 128Mb
256 = 256Mb
512M = 512Mb
01G = 1Gb

■ Package Type

M = 16 pin SOIC 300mil
B = 8 pin SOIC 208mil
N = 8 pin SOIC 150mil
D = 8 pin TSSOP
K = 8 pin WSON (6x5 mm)
L = 8 pin WSON (8x6 mm)
U = 8 pin USON (2x3mm)
T = 8 pin USON (4x3mm)
V = 8 pin VVSOP 150mil
H = 24 ball (BGA 6x8 mm)

■ Lead-free Package

L = Lead-Free (Pb Free) and Halogen Free

■ Temperature Grade

E = Extended grade (-40°C to +105°C)
A3 = Automotive grade (-40°C to +125°C)

■ SPECIAL OPTIONS

J = Standard
Q = QE bit set to 1

Notes: Call Factory for KGD and WLCSP.

Please refer to the datasheet for product specifications and ordering information.